APPENDIX

IN THE CLAIMS

22. A thin film semiconductor device comprising:

a product substrate and a thin film device,

wherein a manufacturing substrate is of an inorganic material,

wherein said product substrate is one of an organic material and a metal,

wherein said product substrate has a first side and a second side opposed to said first side,

wherein said manufacturing substrate is adjacent said first side, said manufacturing substrate being closer to said first side than to said second side,

wherein said thin film device is adjacent said second side, said thin film device being closer to said second side than to said first side,

wherein said product substrate is between said thin film device and said manufacturing substrate,

wherein said manufacturing substrate is removed to expose said first side, thereby leaving said product substrate and said thin film device.

23. A thin film semiconductor device as claimed in claim 22, wherein said manufacturing substrate is a glass substrate.

24. A thin film semiconductor device as claimed in claim 22, wherein said thin film device is a thin film transistor.

25. A thin film semiconductor device as claimed in claim 22, wherein said metal is aluminum.

26. A thin film semiconductor device as claimed in claim 22, wherein said organic material is a plastic.

27. A thin film semiconductor device as claimed in claim 26, wherein a moisture-proof buffer film is formed between said second surface and said thin film device.

28. A thin film semiconductor device as claimed in claim 26, wherein said plastic is from the group comprising polyether sulfone resin, polyethylene terephthalate resin and ARTON resin.

29. A thin film semiconductor device as claimed in claim 22, wherein an adhesive layer is formed between said first surface and said manufacturing substrate.

30. A thin film semiconductor device as claimed in claim 29, wherein said adhesive layer is dissolved to remove said manufacturing substrate.

31. A thin film semiconductor device as claimed in claim 29, wherein said adhesive layer is from the group comprising a polyimide, Teflon resin, silicon, germanium and metal.

32. A liquid crystal display device comprising:

a product substrate and a pixel array,

wherein a manufacturing substrate is of an inorganic material,

wherein said product substrate is one of an organic material and a metal,

wherein said product substrate has a first side and a second side opposed to said first side,

wherein said manufacturing substrate is adjacent said first side, said manufacturing substrate being closer to said first side than to said second side,

wherein said pixel array is adjacent said second side, said pixel array being closer to said second side than to said first side,

wherein said product substrate is between said pixel array and said manufacturing substrate,

wherein said manufacturing substrate is removed to expose said first side, thereby leaving said product substrate and said pixel array.

33. A liquid crystal display device as claimed in claim 32, wherein said manufacturing substrate is a glass substrate.

34. A liquid crystal display device as claimed in claim 32, wherein said metal is aluminum.

35. A liquid crystal display device as claimed in claim 32, wherein said organic material is a plastic.

36. A liquid crystal display device as claimed in claim 35, wherein a moisture-proof buffer film is formed between said second surface and said pixel array.

37. A liquid crystal display device as claimed in claim 35, wherein said plastic is from the group comprising polyether sulfone resin, polyethylene terephthalate resin and ARTON resin.

38. A liquid crystal display device as claimed in claim 32, wherein an adhesive layer is formed between said first surface and said manufacturing substrate.

39. A liquid crystal display device as claimed in claim 38, wherein said adhesive layer is dissolved to remove said manufacturing substrate.

40. A liquid crystal display device as claimed in claim 38, wherein said adhesive layer is from the group comprising a polyimide, Teflon resin, silicon, germanium and metal.

41. A electroluminescence display device comprising:

a product substrate and an electroluminescence device ,

wherein a manufacturing substrate is of an inorganic material,

wherein said product substrate is one of an organic material and a metal,

wherein said product substrate has a first side and a second side opposed to said first side,

wherein said manufacturing substrate is adjacent said first side, said manufacturing substrate being closer to said first side than to said second side,

wherein said electroluminescence device is adjacent said second side, said electroluminescence device being closer to said second side than to said first side,

wherein said product substrate is between said electroluminescence device and said manufacturing substrate,

wherein said manufacturing substrate is removed to expose said first side, thereby leaving said product substrate and said electroluminescence device.

42. A electroluminescence display device as claimed in claim 41, wherein said manufacturing substrate is a glass substrate.

43. A electroluminescence display device as claimed in claim 41, wherein said metal is aluminum.

44. A electroluminescence display device as claimed in claim 41, wherein said organic material is a plastic.

45. A electroluminescence display device as claimed in claim 44, wherein a moisture-proof buffer film is formed between said second surface and said electroluminescence device.

46. A electroluminescence display device as claimed in claim 44, wherein said plastic is from the group comprising polyether sulfone resin, polyethylene terephthalate resin and ARTON resin.

47. A electroluminescence display device as claimed in claim 41, wherein an adhesive layer is formed between said first surface and said manufacturing substrate.

48. A electroluminescence display device as claimed in claim 47, wherein said adhesive layer is dissolved to remove said manufacturing substrate.

49. A electroluminescence display device as claimed in claim 47, wherein said adhesive layer is from the group comprising a polyimide, Teflon resin, silicon, germanium and metal.